

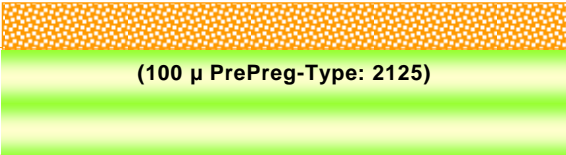
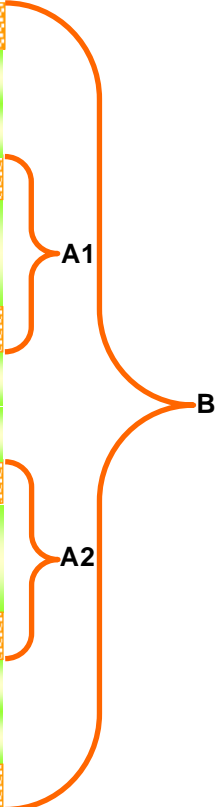




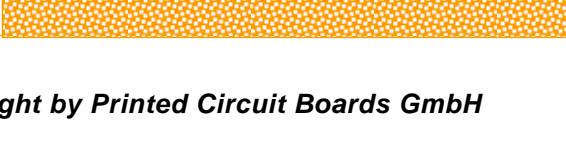

**Schematic Key for Multilayer and HDI-Technology Build-Ups**

a	b	c	d	e	f	g + h + i
---	---	---	---	---	---	-----------

**06 153 FR4 35 L36.35 P10**

columns and equal kind of positions are separated by "\_". Equal prefixes in one column are reduced to one.

**06\_153\_FR4\_35\_L36.35\_p10**

Layers	in $\mu$	Material	Build-Up	Assembly
<b>Layer-1</b>	35 $\mu$	Copper		
	100 $\mu$	Prepreg		
	100 $\mu$	Prepreg		
<b>Layer-2</b>	35 $\mu$	Copper		
	360 $\mu$	L-FR4		
<b>Layer-3</b>	35 $\mu$	Copper		
	100 $\mu$	Prepreg		
	100 $\mu$	Prepreg		
<b>Layer-4</b>	35 $\mu$	Copper		
	360 $\mu$	L-FR4		
<b>Layer-5</b>	35 $\mu$	Copper		
	100 $\mu$	Prepreg		
	100 $\mu$	Prepreg		
<b>Layer-99</b>	35 $\mu$	Copper		

© Copyright by Printed Circuit Boards GmbH